


PATENT NUMBER

ISSUE CLASSIFICATION	
Class	Subclass

U.S. **UTILITY** Patent Application

 O.I.P.E. SCANNED <u>TR3</u> O.A. <u>Am</u>	PATENT DATE
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APPLICATION NO. 09/964709	CONT/PRIOR	CLASS 257	SUBCLASS 706	ART UNIT 2814	EXAMINER CHAMBLISS <i>[Signature]</i>
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APPLICANTS

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Method of improving thermal performance in flip chip/integral heat spreader packages using low modulus thermal interface material

PTO-2040
12/89

ISSUING CLASSIFICATION

[illegible]

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS		CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	_____ (Assistant Examiner)		NOTICE OF ALLOWANCE MAILED _____	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____ _____ _____	_____ (Primary Examiner)		ISSUE FEE Amount Due Date Paid	
	_____ (Legal Instruments Examiner)		ISSUE BATCH NUMBER _____	
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